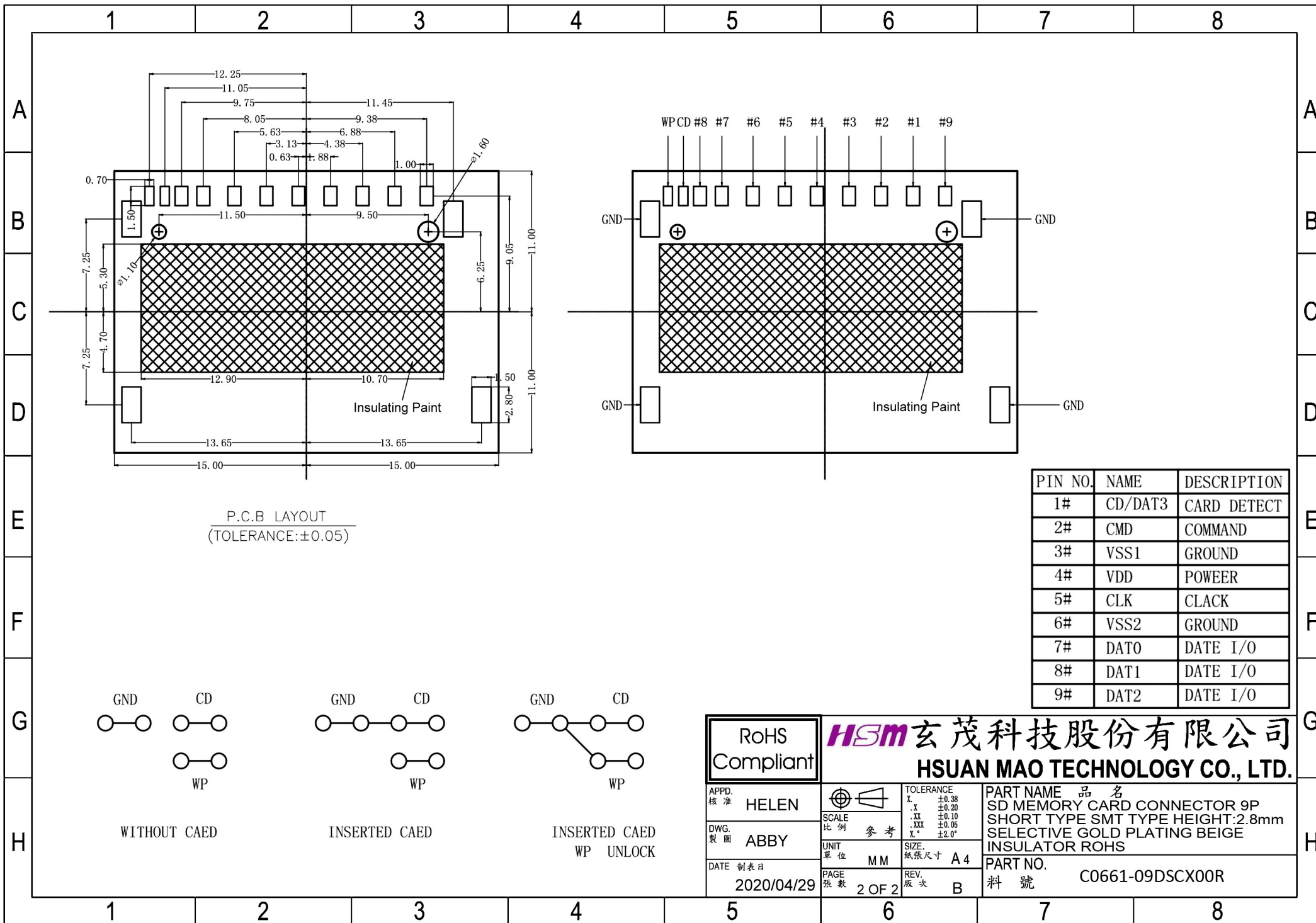


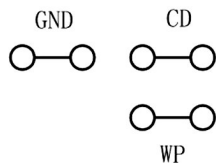
1. MATERIAL:
 - 1.1 INSULATOR: LCP, UL94V-0; COLOR: NATURE/BLACK.
 - 1.2 CONTACT: BRASS T=0.20mm.
 - 1.3 SHELL: BRASS/SPTE, T=0.20mm.
2. FINISH:
 - 2.1 CONTACT: GOLD FLASH PLATED IN CONTACT AREA; 50*MIN. TIN PLATED IN SOLDER AREA 30*MIN. NICKEL UNDERPLATED OVERALL.
 - 2.2 SHELL: 50*MIN. NICKEL PLATED OVERALL.
3. ELECTRICAL CHARACTERISTICS
 - 3.1 CURRENT RATING: AC/DC 0.5A.
 - 3.2 CONTACT RESISTANCE: 20mΩ MAX.
 - 3.3 INSULATION RESISTANCE: 100mΩ MIN DC 500V.
 - 3.4 DIELECTRIC WITHSTANDING VOLTAGE: AC 500V PER MINUTE.
 - 3.5 OPERATING TEMPERATURE: - 25~+85.
4. NOTES:
 - 4.1 THIS COMPONENT AND ITS HOMOGENEOUS SUBCOMPONENTS ARE RoHS2.0 COMPLIANT.
 - 4.2 RESISTANCE TO SOLDERING HEAT: 260 FOR 10 SECONDS.
 - 4.3 COPLANARITY IS 0.1mm MAX.

RoHS Compliant		HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准 HELEN	SCALE 比例 参考	TOLERANCE X ±0.38 Y ±0.20 .XX ±0.10 .XXX ±0.05 X* ±2.0*	PART NAME 品名 SD MEMORY CARD CONNECTOR 9P SHORT TYPE SMT TYPE HEIGHT:2.8mm SELECTIVE GOLD PLATING BEIGE INSULATOR ROHS
DWG. 製圖 ABBY	UNIT 單位 MM	SIZE. 紙張尺寸 A 4	PART NO. C0661-09DSCX00R
DATE 製表日 2020/04/29	PAGE 張數 1 OF 2	REV. 版次 B	料號 C0661-09DSCX00R

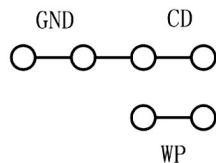


P.C.B. LAYOUT
(TOLERANCE: ±0.05)

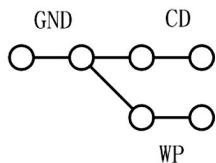
PIN NO.	NAME	DESCRIPTION
1#	CD/DAT3	CARD DETECT
2#	CMD	COMMAND
3#	VSS1	GROUND
4#	VDD	POWEER
5#	CLK	CLACK
6#	VSS2	GROUND
7#	DAT0	DATE I/O
8#	DAT1	DATE I/O
9#	DAT2	DATE I/O



WITHOUT CAED



INSERTED CAED



INSERTED CAED
WP UNLOCK

RoHS
Compliant

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HSUAN MAO TECHNOLOGY CO., LTD.

APPD.
核准 HELEN
DWG.
製圖 ABBY
DATE 制表日
2020/04/29

SCALE
比例 參考
UNIT
單位 MM
PAGE
張數 2 OF 2

TOLERANCE
X. ±0.38
.X ±0.20
.XX ±0.10
.XXX ±0.05
X.* ±2.0°
SIZE
紙張尺寸 A 4
REV.
版次 B

PART NAME 品名
SD MEMORY CARD CONNECTOR 9P
SHORT TYPE SMT TYPE HEIGHT:2.8mm
SELECTIVE GOLD PLATING BEIGE
INSULATOR ROHS
PART NO.
料號 C0661-09DSCX00R